

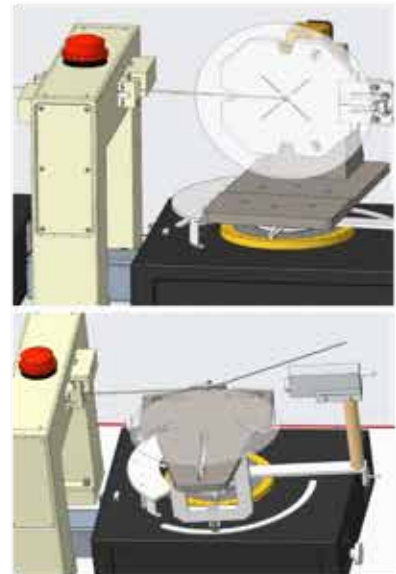
DXL-C1018

Automatically measure the wafer's End face/Reference edge/NOTCH crystal orientation angle, one-button operation data networking.

The Equipment automatically adjusts the wafer, automatically measures and automatically judges the peak value to avoid human error.

Equipment Performance

- The equipment is a Double-work bench.
- One side of the workbench measures the wafer end face and automatically collects grain orientation data in all four directions (0°, 90°, 180°, 270°).
- The other workbench measures the Notch /reference edge and collects data automatically.
- The device rotates the wafer automatically, measures automatically and determines the peak value automatically.
- Calibration-free, eliminating the need for daily device calibration.
- Contains functions: QR code/barcode data import, export of measurement results to the server, automatic calculation of differences, etc.



Item	Parametric
Crystal Diameter	125~300mm, ± 1 mm
Crystal length	Wafer Thickness 0.5mm~2.0mm
Measurement angle	0~50°
Accuracy	$\pm 30''$